<p>| | |</p>
<table>
<thead>
<tr>
<th></th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td>Title</td>
<td>Microstructure and mechanical properties of mechanically alloyed ODS copper alloy for fusion material application</td>
</tr>
<tr>
<td>Author(s)</td>
<td>Aghamiri, S.M.S.; Oono, N.; Ukai, S.; Kasada, R.; Noto, H.; Hishinuma, Y.; Muroga, T.</td>
</tr>
<tr>
<td>Citation</td>
<td>Nuclear Materials and Energy (2018), 15: 17-22</td>
</tr>
<tr>
<td>Issue Date</td>
<td>2018-05</td>
</tr>
<tr>
<td>URL</td>
<td><a href="http://hdl.handle.net/2433/233814">http://hdl.handle.net/2433/233814</a></td>
</tr>
<tr>
<td>Rights</td>
<td>© 2018 The Authors. Published by Elsevier Ltd. This is an open access article under the CC BY-NC-ND license [<a href="http://creativecommons.org/licenses/BY-NC-ND/4.0/">http://creativecommons.org/licenses/BY-NC-ND/4.0/</a>].</td>
</tr>
<tr>
<td>Type</td>
<td>Journal Article</td>
</tr>
<tr>
<td>Textversion</td>
<td>publisher</td>
</tr>
</tbody>
</table>

Kyoto University
Microstructure and mechanical properties of mechanically alloyed ODS copper alloy for fusion material application

S.M.S. Aghamiria,⁎, N. Oonoa, S. Ukab, R. Kasadaa, H. Notoc, Y. Hishinuma, T. Murogac

a Graduate School of Engineering, Hokkaido University, Sapporo 060-8628, Japan
b Institute of Advanced Energy, Kyoto University, Kyoto 611-0011, Japan
c National Institute of Fusion Science, Gifu 509-5202, Japan

A R T I C L E   I N F O

Keywords:
ODS copper
Mechanical alloying
Microstructure
Mechanical properties

A B S T R A C T

Advanced oxide dispersion strengthened copper alloys are promising structural materials for application in divertor system of future fusion reactors due to high irradiation resistance, high thermal conductivity, and good mechanical properties. In this study, a new ODS copper including 0.42wt%Y2O3 nanosized oxide particles was developed successfully by mechanical alloying method using addition of 1 wt% Stearic acid in Ar atmosphere. Mechanical alloying resulted in decrease of crystallite size to 28 nm in concurrent with increment of dislocation density and hardness to the saturated level of 1.7 × 1019m−2 and 226HV0.1 after 48 h milling, respectively. Consolidated ODS copper by SPS and then hot roll-annealing at 900 °C/60 min showed an average grain size of 1.1 µm with a near random texture. Furthermore, TEM observations demonstrated fine semicoherent Y2O3 oxide particles distributed with a misfit parameter (δ) of 0.17 in copper matrix with an average size of 10.8 nm and interparticle spacing of 152 nm. Finally, tensile test evaluation determined comparable mechanical properties of the annealed ODS copper (Cu-0.42wt%Y2O3) with Glidcop-Al25 including a yield strength of 272 MPa and total elongation of 12%, by two mechanisms of grain boundary strengthening and oxide particle strengthening.

1. Introduction

Advanced copper alloys are the main candidate for high heat flux and high temperature materials application in different components of fusion energy reactors such as divertor due to extremely high energy density. Key properties of high thermal conductivity (~300–400 W/m.K), good mechanical property (yield strength >200 MPa) and high irradiation resistance (especially irradiated-condition ductility) are essential for effective performance of these materials in a high heat flux, high irradiation environment [1].

Up to now, two main category of copper alloy have been developed for fusion application: precipitation strengthened (PS) copper alloys and dispersion strengthened (DS) copper alloys [1–4]. PS copper alloys such as CuCrZr (used in ITER reactor) or CuNiBe can be strengthened considerably by fine precipitation of second phase particles. The main problem of PS copper alloys is softening by coarsening of precipitates at intermediate to high temperatures. DS copper alloys have the benefit of keeping the strength even at elevated temperatures by dispersion of fine stable oxide particles. The main commercially available dispersion-strengthened copper alloys are Glidcop-Al15, Al25, Al60 and MAGT 0.2, all produced by internal oxidation method. These alloys are strengthened by dispersion of fine alumina particles inside the copper matrix during their manufacturing process. However, both developed copper alloys have the serious limitation of low ductility after irradiation [5,6].

Oxide dispersion strengthened (ODS) alloys are the attractive option for the irradiation environments because of good mechanical properties and irradiation resistance. It has been proved that dispersion of fine Y2O3 oxide particles in ODS Steels have an important role to keep the mechanical properties and good irradiation resistance by capturing of defects and reducing irradiation swelling [7,8]. Up to now, the best developed way for good dispersion of Y2O3-based oxide particles in different ODS materials is mechanical alloying (MA) [8,9]. However, there is only few studies in literature regarding mechanical alloyed (MAed) ODS copper alloys with a limited progress [10–13]. It is expected to promote the mechanical properties by appropriate dispersion of fine oxide particles in a well-designed copper matrix. To develop new ODS copper with superior properties by MA method, at first, it needs to overcome the severe sticking of milled powder induced by high ductility of copper. Cryo-ball milling by liquid nitrogen has been reported to be used as successful milling method for dispersion of nanosized yttria and calcia in copper alloy [14,15]. In this study, a room temperature
milling was studied in an alloy with a nominal composition of Cu-0.5wt % Y₂O₃ by addition of processing control agent (1 wt% stearic acid (SA)) during milling in Ar atmosphere. After consolidation followed by hot rolling and subsequent annealing at 900 °C, the mechanical properties of the ODS copper alloy were evaluated based on microstructural characterization.

2. Experimental

In this research, a high purity (99.9%) copper powder (particle size of ~50 µm) and Y₂O₃ nanopowder (particle size of ~50 nm) were used as raw materials. The powder mixture was mechanically alloyed by using Fritsch-P6 planetary ball mill with different additions of stearic acid up to 2 wt% as process control agent (PCA) in Ar atmosphere. 1 wt % stearic acid was chosen as the optimum amount based on the higher powder output and purity of MA powder. The ball milling was performed with ball to powder ratio of 10:1 and rotation speed of 470 rpm in different milling times up to 96 h. After the milling, the chemical composition of the powder was analyzed by inductively coupled plasma (ICP) method.

X-ray diffraction was conducted by means of Cu-Ka radiation with a Philips X’Pert PRO to characterize the phases during milling. The change in crystallite size (D) during MA can be calculated from XRD broadening based on the Hall–Williamson equation [16]:

\[
\beta_i \cos \theta = 2 \varepsilon \sin \theta + (K\lambda/D)
\]

where \(\beta_i\) is the peak full width at the half maximum intensity (FWHM) (after subtracting the instrumental broadening), \(\theta\) is the diffraction angle, \(\varepsilon\) is the local strain, \(\lambda\) is the x-ray wavelength of the Cu-Ka (0.154 nm) and \(K\) is the Scherrer constant (0.9), respectively. Moreover, the dislocation density (\(\rho\)) can be correlated in terms of local strain (\(\varepsilon\)) in the following equation [16]:

\[
\rho = 7.14 \left(\frac{\varepsilon}{\theta}\right)^2
\]

where b is Burger’s vector (2.52 × 10⁻¹⁰ m). By measuring \(\theta\) and \(\beta_i\) for the planes of (111), (200), (220), (311) and (222), the crystallite size (D) and dislocation density (\(\rho\)) were calculated and plotted versus milling time. This plot was accompanied with the average Vickers microhardness data of the milled powders measured by a HMV-Micro Hardness Tester-SHIMADZU, under a load of 980 mN by a diamond indentation pyramid indenter and dwell time of 30 s with 10 times repetition. Vickers microhardness measurements were performed on each milled powder in different milling times after mounting the powder into the epoxy resin and polishing the surface.

The MAed ODS copper powder after 48 h milling was consolidated by spark plasma sintering (SPS) at 900 °C/45 min. Then the material was hot rolled at 900 °C with a 50% thickness reduction and a reduction rate of 0.5 mm per pass followed by annealing at 900 °C/60 min. The powder and bulk samples of ODS copper powder were observed by FESEM (JEOL, JSM-6500F) equipped with electron back scatter diffraction (EBSD) detector. To attain inverse pole figure (IPF) and Orientation distribution function (ODF), the EBSD data were analyzed by OIM software. The Sample preparation for EBSD was done by grinding with SiC paper up to 2000 grit and then polishing with 1 µm diamond paste and final polishing with silica suspension. A JEOL JEM-2010 transmission electron microscopy was used to study the oxide particles in the microstructure in high magnification with a voltage of 200 kV. Furthermore, a FEI-Titan STEM (300 kV) equipped with high-angle annular dark field (HAADF) detector and EDS analysis was used to analyze elemental distribution of fine oxide particles. The thin samples for TEM observation were prepared by focused ion beam (FIB) (JEOL, JIB-6460F). For evaluation of oxide particle distribution, the interparticle spacing (\(\lambda\)) was derived from the below equations based on TEM images [9]:

\[
\lambda = 1.2s_l - 2r
\]

\[
I_s = \frac{2\pi r^2}{3\tau}
\]

\[
r = \frac{\pi r^2}{4\tau}
\]

where, \(r\) is the radius, \(\tau\) is the average oxide particle radius, \(s_l\) and \(r^2\) are the averages of \(r^2\) and \(r^3\), respectively. The volume fraction of the dispersed oxide particles was estimated to be 0.0075% and the average distance between the centers of oxide particles is \(l_s\). The average particle size is considered as \(D(2r_s)\).

In order to evaluate mechanical properties, tensile test was performed at room temperature under a strain rate of 1.0 × 10⁻⁴/s using Shimadzu, SSL-1KN tensile machine. Miniaturized size specimens for the tensile test were prepared with a gauge dimension of 5 mm in length, 1.2 mm in width and 0.5 mm in thickness by using an electro-discharge processing machine.

3. Results and discussions

3.1. Microstructure of ODS copper powder processed by MA in Ar atmosphere

Fig. 1 shows the x-ray analyses of Cu-0.5wt%Y₂O₃ powder between 0 and 96 h milling times in Ar atmosphere. In these curves, in addition to peaks of copper matrix, the peaks of carbon compounds related to released PCA (Stearic acid) and yttrium oxide can be observed (as shown in the insets by arrows). However, yttrium oxide peak is hard to distinguish after 24 h milling due to probable decomposition during high energy milling as discussed in different ODS materials [8]. Another point in this figure is broadening of copper peaks with increasing milling time which is the characteristic behavior of high strain mechanically milled powders caused by repeated cold welding, fracturing and rewelding of powder particles during milling [17].

Fig. 2(a) shows the evolution of crystallite size and dislocation density during increasing milling time calculated by Eqs. (1) and (2). The curve demonstrates that crystallite size of powder particles decreases sharply in a short time and reach to the stable size of ~28 nm after about 48 h. In other hand, trend of dislocation density shows a concurrent increase with decreasing crystallite size during milling time and saturates in the level of 1.7 × 10¹⁵/m² after 48 h. Change of Vickers microhardness of milled powders at different milling times in Fig. 2(b) determined consistent result with Fig. 1, i.e. increasing the hardness and reaching to 226HV₀.₁ after steady state condition of 48 h milling.

Fig. 3 illustrates the ODS copper powder after mechanical alloying for 48 h in Ar atmosphere. As shown in this figure, a fine and loose powder with irregular-shaped particles of ~100 µm average size was obtained after the high energy milling. The milling conditions resulted in a high powder recovery of 94% without agglomeration and sticking of ductile copper powder to milling cup by using optimum amount of 1 wt% stearic acid which balanced the rate of cold welding and fracturing of powder particles [17]. The chemical composition of the mechanical alloyed ODS copper powder has been specified in Table 1. This composition indicates a copper alloy containing 0.42 wt% Y₂O₃ oxide particles which suggests dissolution of some oxide powder during evaporation of MA pot atmosphere to replace with Ar. In addition, some minor impurity of iron, Ex. O and carbon were inserted from milling medium, atmosphere and releasing of PCA during high energy milling, respectively. The solute iron can decrease the thermal conductivity and segregation of carbon and Ex. O has been reported to result in intermediate temperature embrittlement [1,13]. So, to reach a sample with higher purity and hence higher thermal conductivity, some modifications in MA and thermal treatment in hydrogen environment [17] need to be done.
3.2. Microstructure of consolidated MAed ODS copper alloy by SPS and then hot roll-annealing

Fig. 4 shows the EBSD results of 48 hours-MAed ODS copper alloy consolidated by SPS and then hot rolling and subsequent annealing at 900 °C/60 min. The IPF map (Fig. 4(a)) shows a fine-grained microstructure with the average grain size of about 1.14 µm including some larger grains up to ∼5 µm resulted from abnormal grain growth probably due to lower pinning force induced by low density of oxide particles. Formation of such a fine grain after sintering is the result of severe plastic deformation during MA which has been observed in different MA-processed ODS alloys [8–10]. Evaluation of grains orientations by ODF map at ϕ2 = 0° (Fig. 4(b)) represents a near random orientation of grains with a weak texture oriented in {110} plane including α-fiber of Goss orientation ([011] <100>) and near to Brass orientation ([011] <211>) and the other Cube orientation ([001] <100>) with a max. intensity of 2.05 times than random. Previous studies [18] on copper show that formation of α-fiber texture is a characteristic texture of some deformed copper alloys and cube orientation usually originates from the recrystallized copper grains. Therefore, this microstructure can be result of deformed-recrystallized condition during MA and subsequent hot roll-annealing.

Fig. 5(a–e) shows the HAADF–STEM image of consolidated ODS copper alloy with corresponding EDS map of existing elements as presented in Table 1. It can be observed many dark oxide particles distributed in the copper matrix enriched in the elements of Y and O, which confirms Y₂O₃ particles have dispersed in the matrix. In addition,

Table 1
Chemical composition of MAed ODS copper powder (wt%) after 48 h milling.

<table>
<thead>
<tr>
<th>Specimen</th>
<th>Fe</th>
<th>Ex. O¹</th>
<th>C</th>
<th>Y₂O₃ b</th>
<th>Cu</th>
</tr>
</thead>
<tbody>
<tr>
<td>MA ODS copper powder</td>
<td>0.15</td>
<td>0.22</td>
<td>0.72</td>
<td>0.42</td>
<td>Balance</td>
</tr>
</tbody>
</table>

¹ Estimated from total oxygen content minus oxygen coupled with Y2O₃ (wt % total oxygen − wt% Y × 0.27).

b Estimated from Y content with assumption that Y exists as Y2O₃ (1.27 × wt% Y).
while Fe shows a homogenous distribution in solution with copper, carbon segregated as fine particles beside the oxide particles or around the porosities at right-top of the images.

Fig. 6(a) illustrates TEM micrograph of consolidated ODS copper alloy suggesting fine $\text{Y}_2\text{O}_3$ nanoparticles were distributed homogenously both inside the grains and grain boundaries. Size distribution of the oxide particles in Fig. 6(b) shows that the oxide particles have a very small size up to 30 nm with an average size ($D$) of 10.8 nm and interparticle spacing ($\lambda$) of 152 nm. Misfit parameter ($\delta$) between interface of oxide particles and copper matrix was calculated.
by the below equation [19]:

$$\delta = \frac{2(d_1 - d_2)}{d_1 + d_2}$$  \hspace{1cm} (6)

where $d_1$ and $d_2$ are interplanar spacing of (220)$_{\text{Cu}}$ and (444)$_{\text{Y}_2\text{O}_3}$ planes with the values of 0.1328 nm and 0.1582 nm, respectively, measured from diffraction pattern in Fig. 6(c). The misfit parameter was calculated to be 0.17 between 0.25 (incoherent particles) and 0.05 (coherent particles). This misfit value indicates a semicoherent interface forms between oxide particles and copper matrix. Analysis of oxide particles according to Ashby-brown contrast [20] shown in Fig. 7 specified that finer oxide particles with the size of 5–15 nm (constituting approximately 85% of total oxide particles based on Fig. 6(b)) have a semicoherent interface (Fig. 7(a)) revealed by moire fringes. The larger oxide particles (remaining ~15% of total oxide particles) with the size of more than 15 nm have an incoherent interface (Fig. 7(b)) with copper matrix.

3.3. Mechanical properties of hot rolled-annealed ODS copper

The engineering stress-strain curve of 48 h-MAed ODS copper alloy (Cu-0.42%wtY$_2$O$_3$) after SPS - hot rolling and subsequent annealing at 900 °C/60 min has been shown in Fig. 8. It can be observed that this developed alloy has a 0.2% yield strength ($\sigma_y$) of 272 MPa with a total elongation (El.) of 12%. Comparing this result with pure copper ($\sigma_y$:65 MPa, El.:45%) [1] shows an improvement of the strength in expense of lower elongation. This level of strength is comparable with Al oxide-dispersed Glidcop-Al25 alloy processed by internal oxidation method with mechanical properties of ($\sigma_y$:296 MPa, El.:19%) [21].

To understand the strengthening mechanisms involved in this new developed ODS copper, it requires to calculate the contributed mechanisms as follow:

(3-1) Grain boundary strengthening

![Fig. 6. a) TEM micrograph showing distribution of oxide particles in consolidated ODS copper alloy, b) size distribution diagram of oxide particles, c) ring diffraction pattern taken from copper matrix and oxide particles.](image)

![Fig. 7. Y$_2$O$_3$ oxide particles in consolidated ODS copper alloy, a) semi-coherent oxide particles, b) incoherent oxide particles.](image)

![Fig. 8. Engineering stress-strain curve of hot rolled-annealed ODS copper alloy.](image)
To calculate the grain boundary effect on strengthening, it was used the Hall–Petch relation as below equation:

$$\sigma_G = \sigma_0 + K_{HP} d^{-1/2}$$  \hspace{1cm} (7)

where $\sigma_0$ is Peierls stress (which is near zero for copper [14]), $K_{HP}$ as Hall–Petch constant (4.5 MPa mm$^{1/2}$ [14]), $d$ as grain diameter (1.14 µm based on the IPF map in Fig. 4b). Based on these values, grain boundary strengthening ($\sigma_{GB}$) is calculated to be 133MPa.

3-2 Oxide particle strengthening

By using Orowan mechanism, the effect of oxide dispersion strengthening based on bypass of oxide particles by dislocation loop was calculated by the following relation:

$$\sigma_O = 0.84 \frac{MGb}{2\pi r} \left(1 - v \left(\frac{3\pi}{2} - \frac{\pi}{4}\right) \ln \left(\frac{\pi r}{4b}\right)\right)$$  \hspace{1cm} (8)

where $M$ is Taylor factor (3.1), $G$ is shear modulus (45.5 GPa), $b$ is Burgers vector (0.255 nm) and $v$ is Poisson's ratio (0.34) [19], $r$ and $f$ are average radius and fraction of oxide particles, respectively (5.4 nm and 0.0075 based on TEM studies in the Section 3.2). The contributed oxide particle strengthening in the ODS copper alloy is calculated to be 272 MPa.

Sum of both grain boundary strengthening (133 MPa) and oxide particle strengthening (127 MPa) result in the total strength ($\sigma_t$) of 260 MPa which is comparable to the yield strength of ODS copper alloy.

4. Conclusions

In this study, a new ODS copper with a composition of Cu-0.42%wt Y$_2$O$_3$ was processed successfully by several processing steps: 1) MA using addition of 1wt% stearic acid in Ar atmosphere, 2) then consolidation by Spark plasma sintering and subsequent hot rolling at 900 °C with 50% reduction and final annealing at 900 °C/60 min. MA of powder after 48 h milling showed a high decrease of crystallite size to 28 nm and increase of dislocation density and consequent Vickers microhardness to a high level of 1.7 $\times$ 10$^{18}$ m$^{-2}$ and 226HV$_{0.01}$, respectively. At this milling time, a fine and loose MA powder was obtained with some minor elements of C, Ex. O and Fe. The microstructure of hot roll-annealed ODS copper showed an average grain size of 1.14 µm containing fine incoherent Y$_2$O$_3$ oxide particles distributed in copper matrix with average grain size of 10.8 nm and interparticle spacing of 152 nm. Based on two contributed mechanisms of grain boundary strengthening and oxide dispersion strengthening, the mechanical properties promoted to a yield strength of 272 MPa and elongation of 12% which shows a comparable result with the Glidcop-A125 alloy and considerable increase of strength in comparison to pure copper.

Acknowledgment

This work is supported by Grant-in-Aid for Scientific Research(A), 16H02443, Japan Society for the Promotion of Science (http://dx.doi.org/10.13039/501100001691).

References